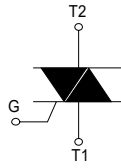
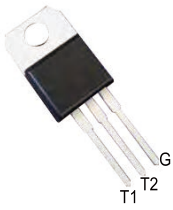
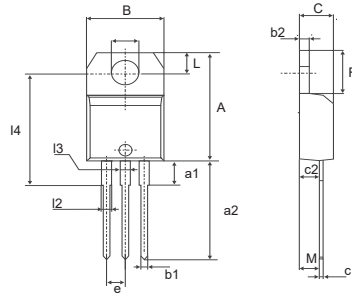


BTA24

Discrete Triacs(Isolated)



Dimensions TO-220AB



REF.	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	15.20	15.90	0.598			0.625
a1		3.75				0.147
a2	13.00		14.00	0.511		0.551
B	10.00		10.40	0.393		0.409
b1	0.61		0.88	0.024		0.034
b2	1.23		1.32	0.048		0.051
C	4.40		4.60	0.173		0.181
c1	0.49		0.70	0.019		0.027
c2	2.40		2.72	0.094		0.107
e	2.40		2.70	0.094		0.106
F	6.20		6.60	0.244		0.259
l1	3.75		3.95	0.147		0.151
H	15.80	16.40	18.80	0.622	0.648	0.661
L	2.65		2.95	0.104		0.116
l2	1.14		1.70	0.044		0.066
l3	1.14		1.70	0.044		0.066
M		2.60			0.102	



	V_{DRM}/V_{RRM} V_{DSM}/V_{RSM}	
	V	V
BTA24-200	200	300
BTA24-400	400	500
BTA24-600	600	700
BTA24-800	800	900
BTA24-1000	1000	1100
BTA24-1200	1200	1300

ABSOLUTE MAXIMUM RATINGS

Symbol	Parameter	Value	Unit
$I_{T(RMS)}$	RMS on-state current (full sine wave)	TO-220AB $T_C = 100^\circ C$	24 A
I_{TSM}	Non repetitive surge peak on-state current (full cycle, T_j initial= $25^\circ C$)	F = 60 Hz t = 16.7 ms	250 A
		F = 50 Hz t = 20 ms	260
I^2t	I^2t Value for fusing	tp = 10 ms	340 A^2s
di/dt	Critical rate of rise of on-state current $I_G = 2 \times I_{GT}$, $\tau_s \leq 100ns$	F = 120 Hz $T_j = 125^\circ C$	50 A/ μs
V_{DSM}/V_{RSM}	Non repetitive surge peak off-state voltage	tp = 10 ms $T_j = 25^\circ C$	$V_{DRM}/V_{RRM} + 100$ V
I_{GM}	Peak gate current	tp = 20 μs $T_j = 125^\circ C$	4 A
PG(AV)	Average gate power dissipation	$T_j = 125^\circ C$	1 W
T_{stg} T_j	Storage junction temperature range Operating junction temperature range		- 40 to + 150 - 40 to + 125 $^\circ C$

ELECTRICAL CHARACTERISTICS ($T_j = 25^\circ C$, unless otherwise specified)

■ SNUBBERLESS and LOGIC LEVEL(3 Quadrants)

Symbol	Test Conditions	Quadrant	BTA24		Unit	
			CW	BW		
$I_{GT}^{(1)}$	$V_D = 12V$ $R_L = 33\Omega$	I - II - III	MAX.	35	50	mA
V_{GT}		I - II - III	MAX.	1.3		V
V_{GD}	$V_D = V_{DRM}$ $R_L = 3.3 k\Omega$ $T_j = 125^\circ C$	I - II - III	MIN.	0.2		V
$I_H^{(2)}$	$I_T = 500mA$		MAX.	50	75	mA
I_L	$I_G = 1.2 I_{GT}$	I - III	MAX.	70	80	mA
		II		80	100	
dV/dt (2)	$V_D = 67\% V_{DRM}$ gate open $T_j = 125^\circ C$		MIN.	500	1000	V/ μs
(di/dt)c(2)	Without snubber $T_j = 125^\circ C$		MIN.	13	22	A/ms

Viso>2500VAC 1min



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Discrete Triacs(Isolated)

■ STANDARD (4 Quadrants)

Symbol	Test Conditions	Quadrant		Value	Unit
$I_{GT}^{(1)}$	$V_D=12V R_L=33\Omega$	I - II - III	MAX.	50	mA
		IV		100	
V_{GT}		ALL	MAX.	1.3	V
V_{GD}	$V_D=V_{DRM} R_L=3.3\Omega T_j=125^\circ C$	ALL	MIN.	0.2	V
$I_H^{(2)}$	$I_T=500mA$		MAX.	80	mA
I_L	$I_G=1.2I_{GT}$	I - III - IV	MAX.	70	mA
		II		160	
$dV/dt^{(2)}$	$V_D=67\% V_{DRM}$ gate open $T_j=125^\circ C$		MIN.	500	V/ μs
$(dV/dt)_c^{(2)}$	$(dI/dt)_c=13.3 A/ms T_j=125^\circ C$		MIN.	10	V/ μs

STATIC CHARACTERISTICS

Symbol	Test Conditions			Value	Unit
$V_{TM}^{(2)}$	$I_{TM} = 24A tp = 380\mu s$	$T_j = 25^\circ C$	MAX.	1.55	V
$V_{to}^{(2)}$	Threshold voltage	$T_j = 125^\circ C$	MAX.	0.85	V
$R_d^{(2)}$	Dynamic resistance	$T_j = 125^\circ C$	MAX.	16	m Ω
I_{DRM}	$V_{DRM} = V_{RRM}$	$T_j = 25^\circ C$	MAX.	5	μA
I_{RRM}		$T_j = 125^\circ C$		3	mA

Note 1: minimum IGT is guaranteed at 5% of IGT max.

Note 2: for both polarities of A2 referenced to A1

THERMAL RESISTANCES

Symbol	Parameter	Value	Unit
$R_{th(j-c)}$	Junction to case (AC)	0.8	$^\circ C/W$
$R_{th(j-a)}$	Junction to ambient	60	$^\circ C/W$

PRODUCT SELECTOR

Part Number	Voltage (xxx)		Sensitivity	Type	Package
	200 V	~ 1200 V			
BTA24	X	X	50 mA	Standard	TO-220AB

OTHER INFORMATION

Part Number	Marking	Weight	Base quantity	Packing mode
BTA24	BTA24	2 g	50	Tube

Sirectifier[®]

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Discrete Triacs(Isolated)

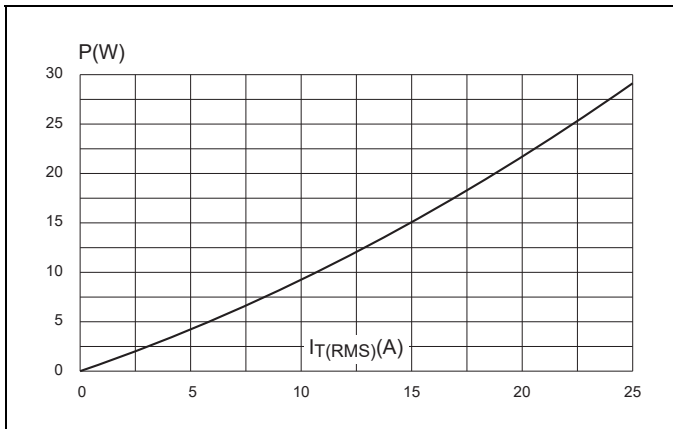


Fig.1 Maximum power dissipation versus RMS on-state current (full cycle).

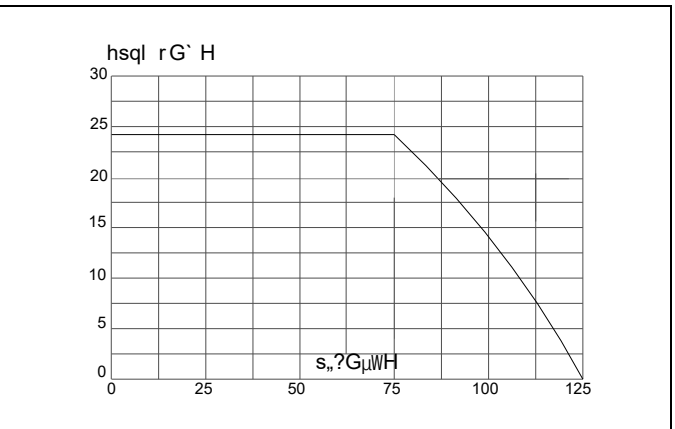


Fig.2-1 RMS on-state current versus case temperature (full cycle).

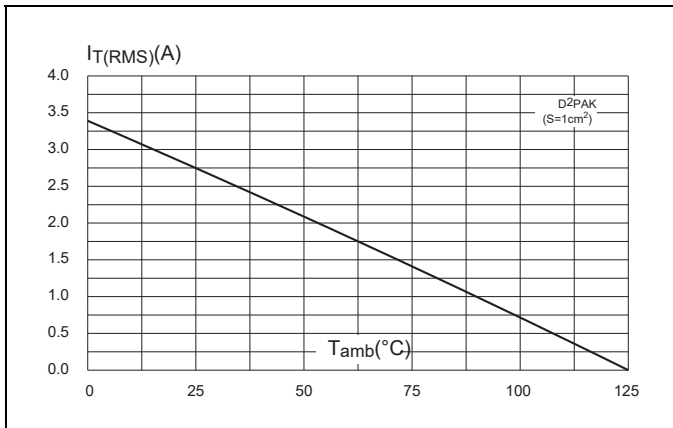


Fig.3 D²PAK RMS on-state current versus ambient temperature (printed circuit board FR4, copper thickness: 35µm) (full cycle)

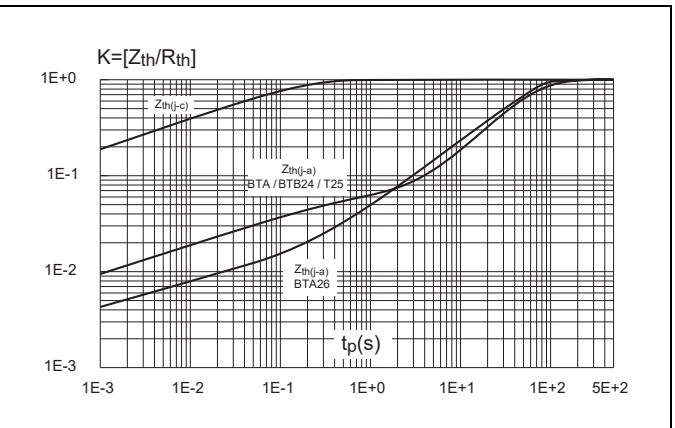


Fig.4 Relative variation of thermal impedance versus pulse duration.

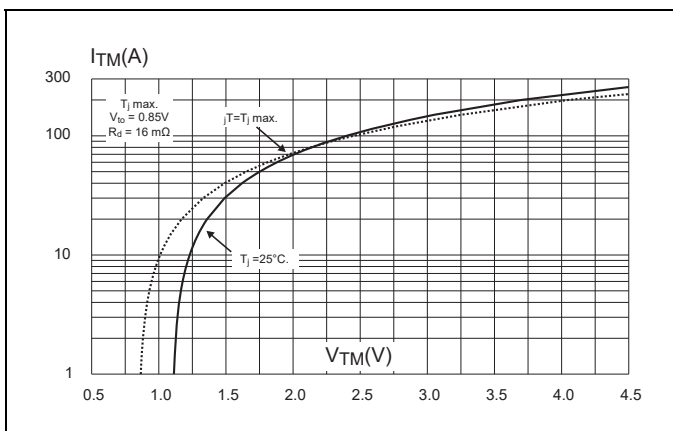


Fig.5 On-state characteristics.

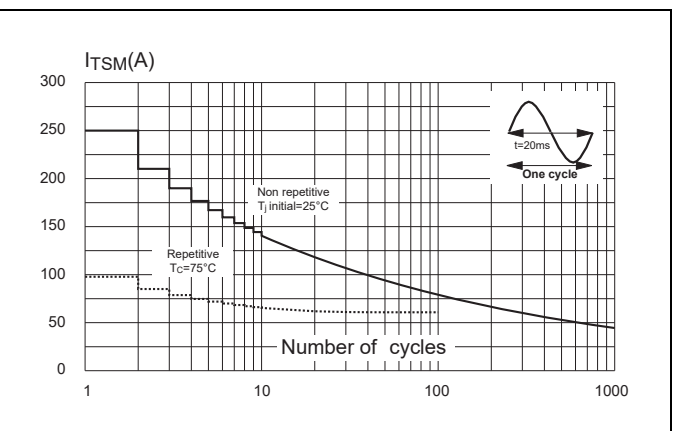


Fig.6 Surge peak on-state current versus number of cycles.

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Discrete Triacs(Isolated)

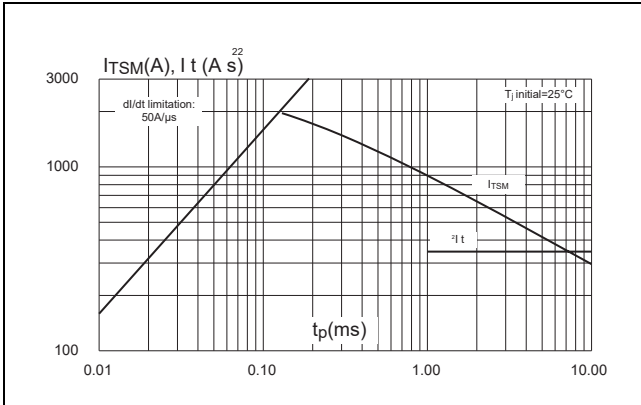


Fig.7 Non-repetitive surge peak on-state current for a sinusoidal pulse with width $t_p < 10$ ms and corresponding value of I^2t

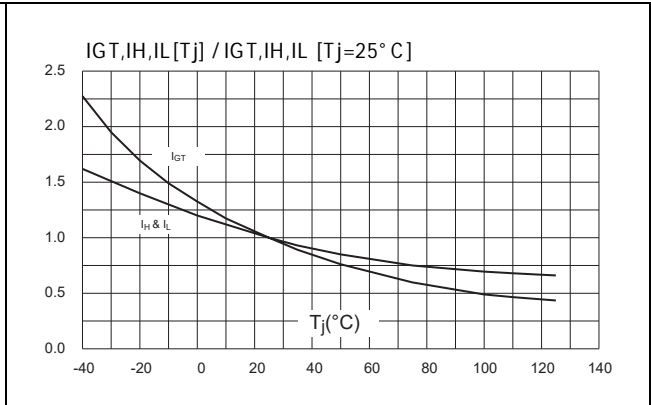


Fig.8 Relative variation of gate trigger current, holding current and latching current versus junction temperature (typical values)

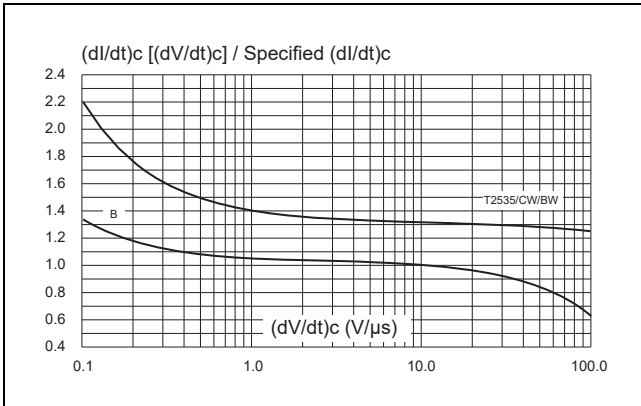


Fig.9 Relative variation of critical rate of decrease of main current versus $(dV/dt)_c$ (typical values)

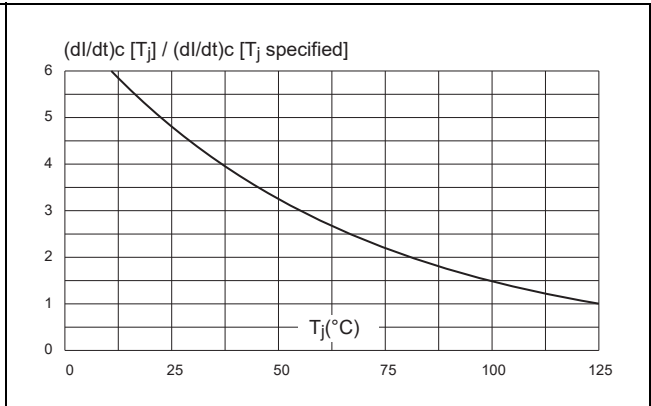


Fig.10 Relative variation variation of critical critical rate rate of decrease of decrease of main current t versus T_j .

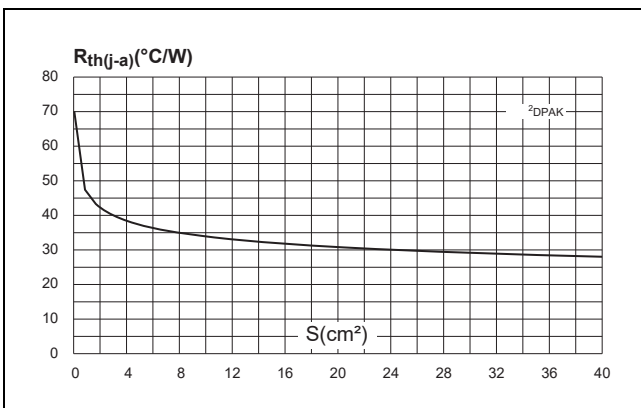


Fig.11 D²PAK thermal resistance junction to ambient versus copper surface under tab (printed circuit board FR4, copper thickness: 35 μ m)